

# PFM-540I

AMD LX-800+CS5536 PC/104 Board

## Thermal Image Analysis Report

Report NO: 08E080013

Release Date: Jun 27 2008

2008/06/27

Issue Stamp

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Manager

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# Thermal Image Analysis

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**I . Model Name: PFM-540I B1.0**

**II . Description: AMD LX-800+CS5536 PC/104 Board**

**III . Date: Jun 16 2008**

**IV . Measure Site: AAEON QE Dept.**

**V . Issued by : Eva Yeh**

**VI. Equipment:**

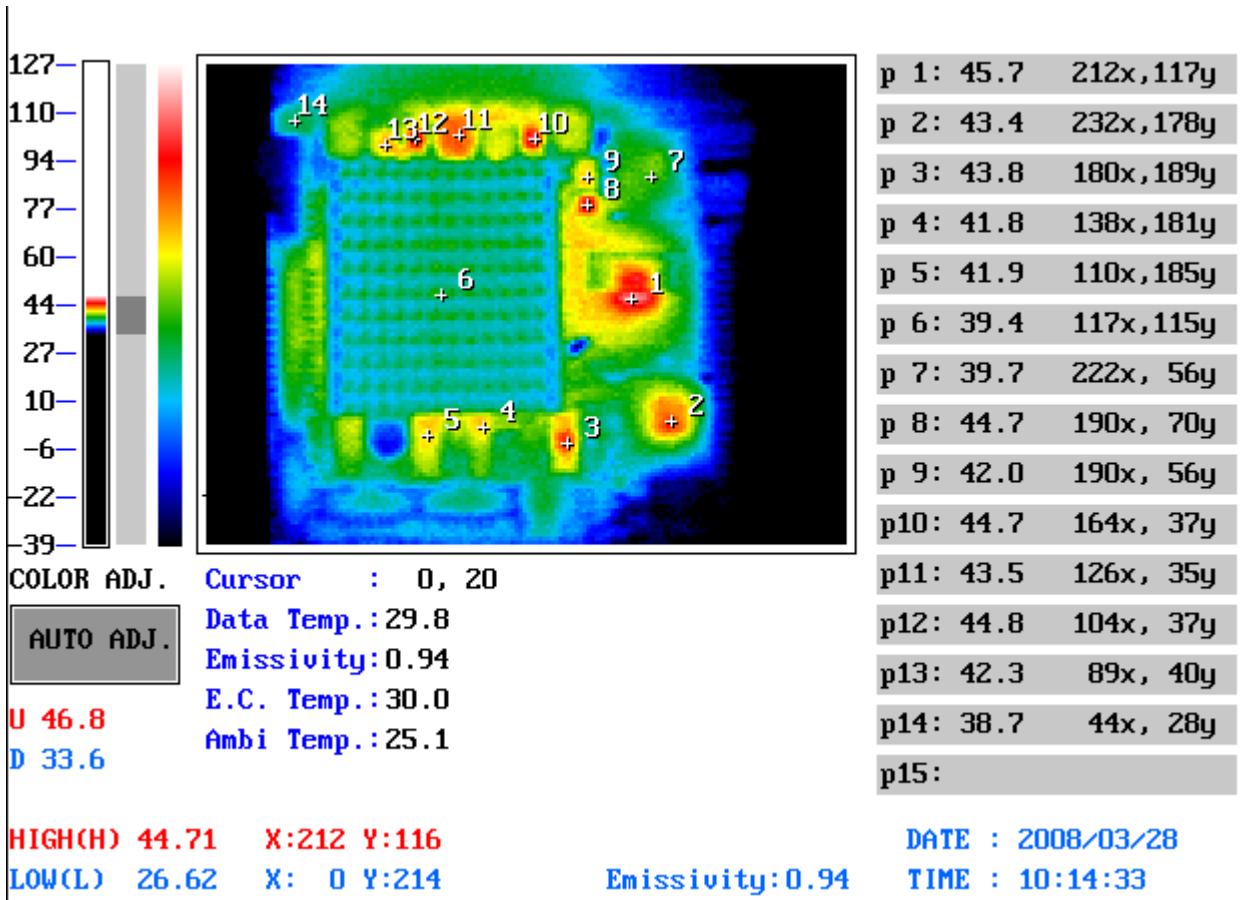
**TVS-100 series by NIPPON AVIONICS CO., LTD.**

**VII. Simulation Environment:**

- **Temperature: Component Side-1 : 25.1°C , Component Side-2 : 25.1°C**
- **CPU : AMD LX-800 500 MHz**
- **RAM : Kingston KVR333X64SC25 DDR333 SODIMM 512MB (NANYA NT5DS64M8BS-5T)**
- **BIOS : PFM-540I BIOS Rev B 0.8 (03/06/2008)**
- **OS : Windows XP Professional English Version V2002 Service Pack 2**
- **CF Card : N/A**
- **HDD : Seagate ST3160815A 160GB**
- **Power : ZECK ZKS-300W AT Power**
- **Application Software: Run Prime95 under Windows XP Professional V2002 Service Pack 2**
- **Take Picture Time: After Power on 2 hours.**

## Temperature Profile Test:

### Component Side-1:

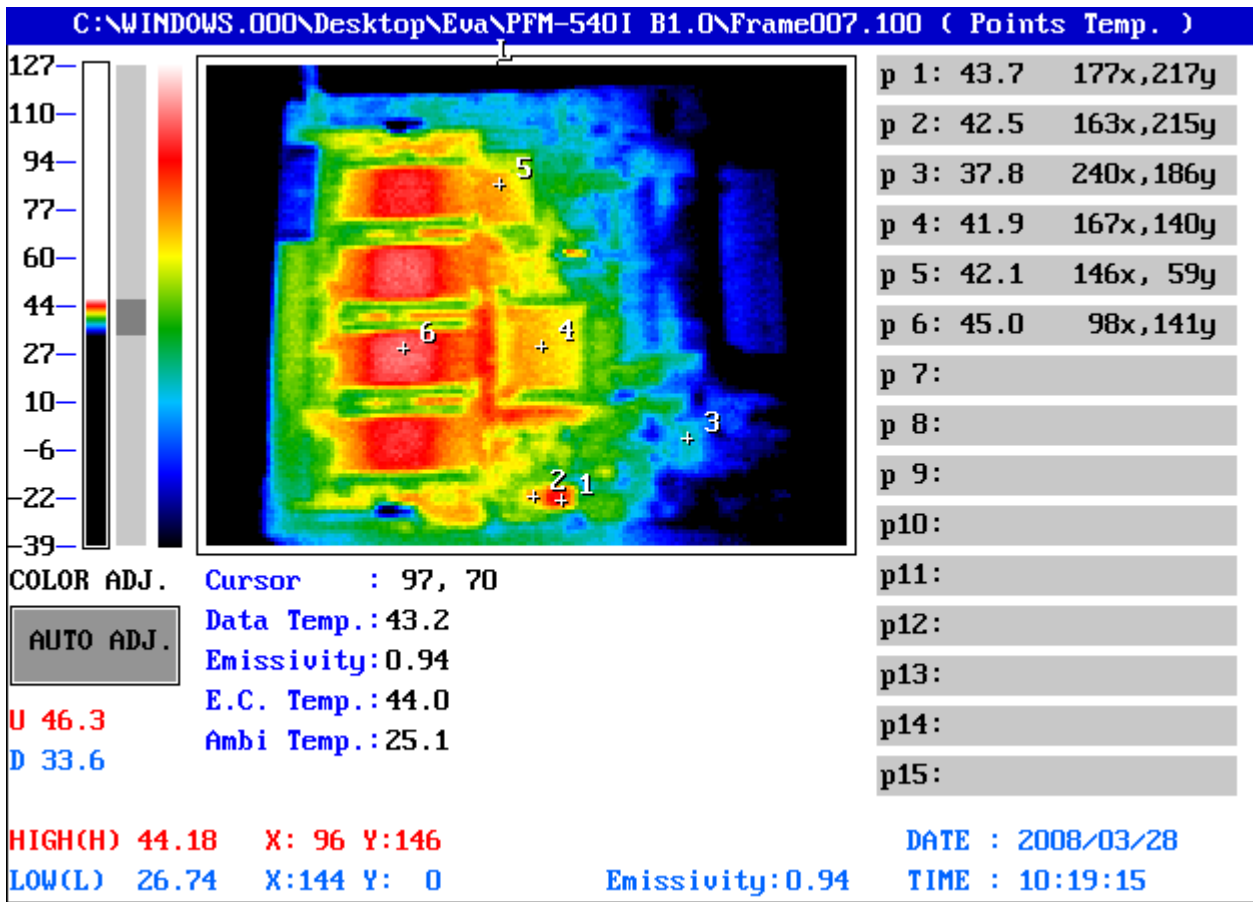


Point	Position	Describe	Tc (°C)	Tm (25.1°C)	Tm (60°C)	Note
1	U6	(TF)IC.SMD 208PBGA.I/O Companion.Multi-Function South Bridge.AMD.CS5536AD;EE-A061313;14S4553600;TWN	110	45.7	80.6	
2	U7	(TF)IC.SMD PBGA 196P.PCI Ethernet 10/100BaseT.Intel.LU82551ER;EE-A031178;14S4255101;TWN	85	43.4	78.3	
3	U10	(TF)IC.SMD.SSOP28.Clock Generator.ICS.MK1491-09FLN;EE-A051233;14S3149103;TWN	100	43.8	78.7	
4	U8	(TF)IC.SMD.SO8.RS-485 Transceiver.Analog.ADM485ARZ;EE-A071696;14S4048503;TWN	85	41.8	76.7	
5	U11	(TF)IC.SMD.SSOP RS232 Driver ESD 15KV.AD.ADM213EARSZ;EE-A970562;14S4021301;TWN	85	41.9	76.8	
6	U5	(TF)AMD CPU.BGU481.LX-800.500MHz.1.25V. AMD.ALXD800EEXJ2VD C3;EE-A080020;14S4800004;TWN	85	39.4	74.3	
7	U3	(TF)IC.SMD TFBGA.160P.PCI to ISA Bridge Chip.ITE.IT8888G-L;EE-A051091;14S4888801;TWN	70	39.7	74.6	

8	U4	(TF)IC.SMD MLPD-10.PWM BUCK CONTROLLER. IR.IR3624MTRPBF;EE-A061341;14S2362400;TWN	125	44.7	79.6	
9	Q2	(TF)Dual N-Channel.SO-8.SMD.Vds=30V.Ids=6A.Rds=21/27mohm.Vgs=10/4 .5V.ANPEC.APM7313KC-TRL;EE-A060563;1315731310;TWN	125	42.0	76.9	
10	U2	(TF)IC.SMD MLPD-10.PWM BUCK CONTROLLER.IR.IR3624MTRPBF;EE-A061341;14S2362400;TW N	125	44.7	79.6	
11	L3	(TF)COIL.1.5uH.Irms=9A.Isat=18A.20%.SMD(7.3x6.8x3.0).2pin.RD C=15m Ohm.GOTREND.GSTC063P-1R5MN; EE-A061612;121110156A;TWN	125	43.5	78.4	
12	U1	(TF)IC.SMD MLPD-10.PWM BUCK CONTROLLER.IR.IR3624MTRPBF;EE-A061341;14S2362400;TW N	125	44.8	79.7	
13	Q1	(TF)Dual N-Channel.SO-8.SMD.Vds=30V.Ids=6A.Rds=21/27mohm.Vgs=10/4 .5V.ANPEC.APM7313KC-TRL;EE-A060563;1315731310;TWN	125	42.3	77.2	
14	TC1	(TF)SP CAP.[8.2 $\mu$ F ~ 470 $\mu$ F].[2V ~ 8V].20%.SMD.Panasonic.EEF/ECG 系列(耐溫 260 °C);EE-A060158;118*****8*;TWN	105	38.7	73.6	

1. Tm (Measured operation temperature) must be less than Tc (Specified case temperature) +5 degree C  
2. Any Tm value showed in **red words** which meaning the value is over the Tc+ 5 degree C of this device specification

## Component Side-2:



Point	Position	Describe	Tc (°C)	Tm (25.1 °C)	Tm (60°C)	Note
1	TC3	(TF)SP CAP.[8.2 μ F~470 μ F].[2V~8V].20%.SMD.Panasonic.EEF/ECG 系列(耐溫 260 °C);EE-A060158;118*****8*;TWN	105	43.7	78.6	
2	Q7	(TF)Dual N-Channel.SO-8.SMD.Vds=30V.Ids=6A.Rds=21/27mohm.Vgs=10/4 .5V.ANPEC.APM7313KC-TRL;EE-A060563;1315731310;TWN	125	42.5	77.4	
3	U16	(TF)IC.SO8 SMD.Voltage Detecting.System Resetting IC.MITSUBISHI.M51957A;EE-A060753;14S4195710;TWN	85	37.8	72.7	
4	N/A	(TF)IC.SMD.PLCC 32P.8M Bit Flash Memory.SST.49LF008A-33-4C-NHE;EE-A070587;14S6200800;TWN	85	41.9	76.8	
5	U28	(TF)IC.SMD.VTQF-128Pin.Super I/O.SMSC.SCH3114-NU;EE-A080482;14S4311401;TWN	100	42.1	77	
6	Memory	Kingston KVR333X64SC25 DDR333 SODIMM 512MB (NANYA NT5DS64M8BS-5T)	N/A	45.0	79.9	


1. Tm (Measured operation temperature) must be less than Tc (Specified case temperature) +5 degree C
2. Any Tm value showed in **red words** which meaning the value is over the Tc+ 5 degree C of this device specification